

In The Claims:

Claims 1-218 (canceled)

219. (new) A chip package comprising:

a preformed substrate comprising semiconductor material, said preformed substrate having no circuitry;

only one preformed die joined with said preformed substrate; and

a patterned line over said only one preformed die and over said preformed substrate.

220. (new) The chip package in claim 219, wherein said preformed die comprising a thin-film circuit layer formed therein, said patterned line having a thickness greater than that of said thin-film circuit layer.

221. (new) The chip package in claim 219, wherein said patterned line comprises a power bus.

222. (new) The chip package in claim 219, wherein said patterned line comprises a ground bus.

223. (new) The chip package in claim 219, wherein said patterned line connects multiple portions of said only one preformed die.

224. (new) The chip package in claim 219 further comprising an insulating layer between said only one preformed die and said patterned line.

225. (new) The chip package in claim 224, wherein said insulating layer comprises polyimide.

226. (new) The chip package in claim 224, wherein said insulating layer comprises benzocyclobutene (BCB).

227. (new) The chip package in claim 224, wherein said insulating layer comprises a porous chip package.

228. (new) The chip package in claim 219 further comprising an insulating layer over said patterned line.

229. (new) The chip package in claim 228, wherein said insulating layer comprises polyimide.

230. (new) The chip package in claim 228, wherein said insulating layer comprises benzocyclobutene (BCB).

231. (new) The chip package in claim 228, wherein said insulating layer comprises a porous chip package.

232. (new) The chip package in claim 219 further comprising an insulating layer on said patterned line, and further comprising another patterned line on said insulating layer.

233. (new) The chip package in claim 232, wherein said insulating layer comprises polyimide.

234. (new) The chip package in claim 232, wherein said insulating layer comprises benzocyclobutene (BCB).

235. (new) The chip package in claim 232, wherein said insulating layer comprises a porous chip package.

236. (new) The chip package in claim 219 further comprising a passive device over said preformed substrate.

237. (new) The chip package of claim 236, wherein said passive device comprises a capacitor.

238. (new) The chip package of claim 236, wherein said passive device comprises an inductor.

239. (new) The chip package of claim 236, wherein said passive device comprises a resistor.

240. (new) The chip package of claim 236, wherein said passive device comprises a filter.

241. (new) The chip package of claim 236, wherein said passive device comprises a wave guide.

242. (new) The chip package of claim 236, wherein said passive device comprises a micro electronic mechanical sensor (MEMS).

243. (new) The chip package in claim 219 further comprising a passive device, said only one preformed die having a top surface and a lower surface, said preformed substrate being under said lower surface of said only one preformed die, said top surface of said only one preformed die being at a horizontal level, wherein said passive device is over said horizontal level.

244. (new) The chip package of claim 243, wherein said passive device comprises a capacitor.

245. (new) The chip package of claim 243, wherein said passive device comprises an inductor.

246. (new) The chip package of claim 243, wherein said passive device comprises a resistor.

247. (new) The chip package of claim 243, wherein said passive device comprises a filter.

248. (new) The chip package of claim 243, wherein said passive device comprises a wave guide.

249. (new) The chip package of claim 243, wherein said passive device comprises a micro electronic mechanical sensor (MEMS).

250. (new) The chip package of claim 243, wherein an opening is in said preformed substrate and accommodates said only one preformed die.

251. (new) The chip package of claim 250, wherein said only one preformed die has a top surface substantially coplanar with that of said preformed substrate.

252. (new) The chip package of claim 219, wherein said preformed substrate comprises a first layer and a second layer, said first layer being on said second layer, an opening being in said first layer and exposing said second layer, and said preformed die being in said opening.

253. (new) The chip package of claim 252, wherein said first layer comprises semiconductor material.

254. (new) The chip package of claim 252, wherein said first layer comprises silicon.

255. (new) The chip package of claim 252, wherein said second layer comprises metal.

256. (new) The chip package of claim 252, wherein said only one preformed die has a top surface substantially coplanar with that of said first layer.

257. (new) The chip package of claim 219 further comprising an insulating layer over said preformed substrate and around said only one preformed die.

258. (new) The chip package of claim 257, wherein said insulating layer comprises polymer.

259. (new) The chip package of claim 257, wherein said insulating layer comprises epoxy.

260. (new) The chip package of claim 219 further comprising a bump on said patterned line.

261. (new) The chip package of claim 260, wherein said bump comprises solder.

262. (new) The chip package of claim 260, wherein said bump comprises gold.

263. (new) The chip package in claim 219, wherein said only one preformed die comprises multiple active devices, and said patterned line connects said multiple active devices.

264. (new) The chip package in claim 219, wherein said preformed substrate comprises silicon.

265. (new) The chip package in claim 219, wherein said patterned line comprises copper.

266. (new) The chip package in claim 219, wherein said only one preformed die has an active surface and a backside surface, said preformed substrate being under said backside surface of said only one preformed die, and said patterned line being over said active surface of said only one preformed die.

267. (new) The chip package in claim 219, wherein said patterned line further comprises a portion not over said only one preformed die.